

PATENT
IBM Docket No. DE20010027US2
Serial No. 10/697,744

Amendments to the Claims

Claim 1 (newly amended) A method of forming a press-lift integrated chip package comprising forming a laminate base structure having plated through holes for introducing press-fit elements, forming a laminate cover structure formed from organic multilayer thin film packages providing very fine conducting paths and having a top mounting plane for mounting chips, and forming a hybrid structure comprised of said laminate surface structure and said laminate cover structure.

Claim 2 (newly amended) A method of forming a press-fit integrated chip package comprising forming a laminate base structure having plated through holes for introducing press-fit elements, forming a laminate cover structure formed from organic multilayer thin film packages providing very fine conducting paths and having a top mounting plane for mounting chips, and forming a sandwich structure being comprised of said laminate surface structure and said laminate cover structure, whereby said structures are subsequently mechanically and electrically conductive connected to each other.

Remarks

The Examiner has suggested an alternate title and has objected to the abstract for being longer than the required 150 words. The undersigned has reviewed the application, including the abstract and the suggested title and respectfully disagrees. The suggested title of "Method for Adjusting the ESR of multilayer component" seems to belong to a different application. In addition, the current abstract in this application is only 5 lines long, so it conforms to the rules.